

October 19, 2004

SUBJECT: Notification of Qualification, MIL-PRF-31032, CAGE Code 0BX48

Mr. Lance Arlander
Titan PCB East, Inc.
2 Industrial Way
Amesbury, MA 01913

Dear Mr. Arlander:

Qualification of your products is granted under the current issue of the specification as a result of successful qualification testing to Department of Defense Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specifications MIL-PRF-31032/1A, /2, /4. The material and classification indicated below shall be listed on Qualified Manufacturers List QML-31032. The effective date of this qualification is June 17, 2004.

Test report number **31032-942-04** has been assigned to your test data. This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Manufacturers are required to inform this office immediately if a failure occurs during PCI testing, if production of this qualification is discontinued, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML products. This letter acts as a letter of delegation in accordance with Chapter 1.4.1 of DLAD 5000.4 and VI.C.1.c of DLAR 4120.13 for your local Government QAR to survey your facility listed above for compliance, as necessary.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Jeffrey Ciesla, (614) 692-0624.

MANUFACTURER NAME & ADDRESS Titan PCB East, Inc. 2 Industrial Way Amesbury, MA 01913	BASIC PLANT LOCATION SAME	CAGE CODE: 0BX48 CONTACT: Lance Arlander PHONE: (978) 388-5740 FAX: (978) 388-5538 EMAIL: Larlander@titaneast.com
Capabilities By Technology / Printed Board Type		QUALIFICATION LETTER
MIL-PRF-31032/1A, /2 Base Material GF (Woven E-Glass, Epoxy resin) Panel Size 18 X 24” Max. Board Thickness 0.125” Min Hole Size 0.012” Aspect Ratio 10:1 Number of Layers 14 Min. Conductor Width 0.004” Min. Conductor Spacing 0.004” Part Mounting THM, SMT, MIX Finish System Hot Air Solder Level (HASL) Hole Preparation Plasma Etchback Copper Plating Electroplated Acid Copper Solder Resist Dry Film		VQ-04-006518

MANUFACTURER NAME & ADDRESS Titan PCB East, Inc. 2 Industrial Way Amesbury, MA 01913	BASIC PLANT LOCATION SAME	CAGE CODE: 0BX48 CONTACT: Lance Arlander PHONE: (978) 388-5740 FAX: (978) 388-5538 EMAIL: Larlander@titaneast.com
Capabilities By Technology / Printed Board Type		QUALIFICATION LETTER
MIL-PRF-31032/4 Base Material GF (Woven E-Glass, Epoxy resin) Flex Base Material GF (Woven E-Glass, Epoxy resin) Panel Size 18 X 24" Max. Board Thickness 0.125" Min Hole Size 0.012" Aspect Ratio 10:1 Number of Layers 14 Min. Conductor Width 0.004" Min. Conductor Spacing 0.004" Part Mounting THM, SMT, MIX Finish System Hot Air Solder Level (HASL) Hole Preparation Plasma Etchback Copper Plating Electroplated Acid Copper Solder Resist Dry Film Flex Usage Flex During Installation (Class A)		VQ-04-006518

Sincerely,

ROBERT P. EVANS
Chief
Sourcing and Qualifications Unit

Visit us on the web at http://www.dscc.dla.mil/offices/sourcing_and_qualification